

Serial No. 10/678,830
File Date: October 3, 2003

Examiner: Lee D. Wilson
Art Unit: 3723

LISTING OF CLAIMS

1 – 21 (canceled)

22. (currently amended) A method for forming a chemical mechanical polishing pad comprising an interior segment and an outer surface, said method comprising:

- a. Providing the interior segment of the chemical mechanical polishing pad;
- b. Coating the interior segment of the chemical mechanical polishing pad with a film with comprising a material selected from the group consisting of Teflon and metals, to form the outer surface of the chemical mechanical polishing pad;

wherein the outer surface is at least 0.05 microns thick.

23. (previously presented) A method according to claim 2 wherein the coating occurs by at least one method selected from the group consisting of dip, spray, spin-coating, vacuum metallization, sputtering and electroless plating.

24. (previously presented) A method of forming a chemical mechanical polishing pad comprising an interior segment and an outer surface, said method comprising:

- a. providing the interior segment of the chemical mechanical polishing pad;
- b. forming the outer surface of the chemical mechanical polishing pad using a portion of the interior segment, by contacting said portion of the interior segment with radiation such that the physical properties of the outer surface are changed in relation to the physical properties of the remainder of the interior segment as a result of the contact with radiation.

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25. (previously presented) A method according to claim 24 wherein the radiation is selected from the group consisting of electron beam radiation, ultra violet radiation and infrared radiation.
26. (previously presented) A method according to claim 24 wherein the radiation is selected from the group consisting of electron beam radiation and infrared radiation.